

Serial No. 10/796,360

In the Claims:

Please amend the claims as follows:

1. (currently amended) A light emitting diode assembly comprising:
 - a prepackaged light emitting diode assembly including:
 - a front luminescent portion, and
 - a mounting base, said mounting base having a heat transfer plate on a rear surface thereof and a first and second electrical contact lead leads extending from the sides thereof;
 - a mounting die, said mounting die being thermally conductive, said mounting die having a bottom surface and a side wall extending upwardly from said bottom surface, said bottom surface and said side wall cooperating to form a cavity therein, wherein said prepackaged light emitting diode assembly is received in said cavity with said heat transfer plate in thermal communication with said bottom surface of said mounting die.
2. (previously presented) The light emitting diode assembly of claim 1, wherein said first contact lead of said prepackaged light emitting diode assembly is in electrical communication with said mounting die.
3. (previously presented) The light emitting diode assembly of claim 1, further comprising:
 - a hole in said rear surface of said mounting die corresponding to said second contact lead of said light emitting diode disposed to prevent said second contact lead of said prepackaged light emitting diode assembly from contacting said mounting die.
4. (previously presented) The light emitting diode assembly of claim 3, wherein said first contact lead of said prepackaged light emitting diode assembly is in electrical communication with said mounting die.
5. (previously presented) The light emitting diode assembly of claim 4, further comprising:

Serial No. 10/796,360

a circuit board adjacent to said mounting die, said circuit board in electrical communication with said second contact lead of said prepackaged light emitting diode assembly.

6. (previously presented) The light emitting diode assembly of claim 5, further comprising:

means for fastening said prepackaged light emitting diode assembly, said mounting die and said circuit board to form a single assembly.

7. (previously presented) A heat sink assembly for mounting a prepackaged light emitting diode assembly comprising:

a mounting die, said mounting die having a bottom wall and a side wall extending upwardly from said bottom wall, said side wall and said bottom wall cooperating to form an interior cavity, said interior cavity being configured to receive a prepackaged light emitting diode assembly, wherein a luminescent portion of said prepackaged light emitting diode assembly directs light output outwardly from said cavity; and

means for conducting heat from said prepackaged light emitting diode assembly to said mounting die.

8. (previously presented) The heat sink assembly of claim 7, wherein said means for conducting heat is a heat transfer plate on a rear surface of said prepackaged light emitting diode assembly, said heat transfer plate being in thermal communication with said bottom wall of said mounting die.

9. (previously presented) The light emitting diode assembly of claim 7, further comprising:

means for fastening said prepackaged light emitting diode assembly to said mounting die to form a single assembly.

10. (currently amended) A flashlight assembly comprising:

Serial No. 10/796,360

at least one battery, said battery having a first electrical contact and a second electrical contact, said first contact;

a flashlight head assembly connected to said at least one battery and including,

a prepackaged light emitting diode assembly having a front luminescent portion and a rear mounting base, said mounting base having a heat transfer plate on a rear surface thereof and a first and second contact lead extending from the sides thereof,

a mounting die, said mounting die being thermally conductive, said mounting die having a bottom surface and a side wall extending upwardly from said bottom surface, said bottom surface and said side wall cooperating to form a cavity therein, wherein said prepackaged light emitting diode assembly is received in said cavity with said heat transfer plate in thermal communication with said bottom surface of said mounting die, wherein said mounting die conducts heat away from said light emitting diode,

an exterior enclosure; and

means for selectively energizing said prepackaged light emitting diode assembly disposed between and in electrical communication with said first and second contacts of said battery and said first and second contacts on said prepackaged light emitting diode assembly.